

ABSOLUTE MAXIMUM RATINGS

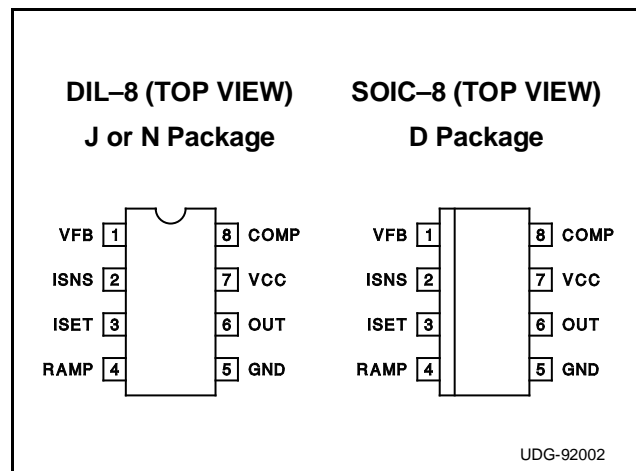
Supply Voltage (Low-impedance Source).....	30.0V
Supply Current (High-impedance Source)	30.0mA
OUT Current, Peak	±1.0A
OUT Energy, Capacitive Load.....	5.0μJ
Input Voltage, ISNS	±5.0V
Input Voltage, VFB.....	-0.3V to +10.0V
COMP Current.....	±10.0mA
ISET Current.....	-10.0mA
Power Dissipation at Ta≤25°C (Note 3)	1.0W
Storage Temperature	-65°C to +150°C
Lead Temperature (Soldering, 10 Seconds).....	+300°C

Note 1: All voltages with respect to GND (Pin 1).

Note 2: All currents are positive into the specified terminal.

Note 3: Refers to DIL-8 Package. Consult Packaging Section of Unitrode Integrated Circuits databook for thermal limitations and considerations of package.

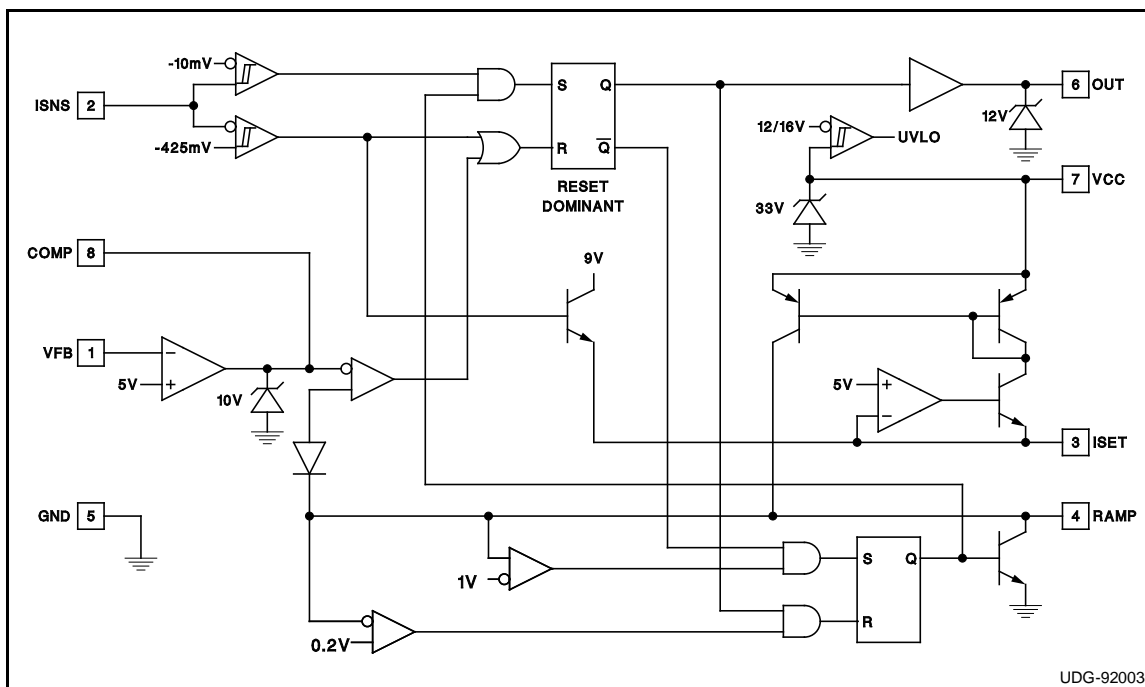
CONNECTION DIAGRAM



ELECTRICAL CHARACTERISTICS Unless otherwise stated, VCC=24V, ISET=50kΩ to GND, RAMP=1nF to GND, ISNS=-0.1V, VFB connected to COMP, no load on OUT, -55°C<Ta<+125°C for the UC1852, -40°C<Ta<+85°C for the UC2852, and 0°C<Ta<+70°C for the UC3852, and Ta=Tj.

PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Timer Section					
ISET Voltage		4.5	5.0	5.5	V
RAMP Charge Current	RAMP=2.5V	88	98	108	μA
RAMP Discharge Current	ISNS= -1.0V, RAMP=1.0V	12	28	50	mA
RAMP Saturation Voltage	ISNS= -1.0V, IRAMP=100μA		0.006	0.200	V
RAMP Threshold - Maximum Frequency	VFB=10V, COMP open	0.92	1.02	1.12	V
RAMP Threshold - PWM Comparator		3.9	4.3	4.8	V
Current Sense Comparator					
ISNS Restart Threshold		-18	-10	-4	mV
ISNS Fault Threshold		-550	-450	-350	mV
ISNS Input Current		-100	-30	100	μA
Error Amplifier Section					
VFB Input Voltage		4.6	5.0	5.3	V
VFB Input Bias Current		-5.00	-0.03	5.00	μA
COMP Sink Current	COMP=7.5V	10			mA
COMP Source Current	COMP=2.5V	-300	-175	-100	μA
COMP Clamp Voltage	VFB=0.0V, COMP open	9.2	10.0	10.6	V
OUT Output					
OUT Saturation Voltage High	VCC=13V, IOUT= -200mA, RAMP=2V	0.5	1.7	2.5	V
OUT Saturation Voltage Low	IOUT=200mA, ISNS= -1.0V	0.5	1.6	2.2	V
OUT Saturation Voltage Low @ 10mA	IOUT=10mA, ISNS= -1.0V		0.05	0.40	V
OUT Clamp Voltage	IOUT= -200mA, RAMP=2V	10.0	12.0	14.5	V
OUT Voltage during UVLO	IOUT=100mA, VCC=0V	0.5	1.0	2.2	V
Overall Section					
Inactive Supply Current	VCC=10V	0.2	0.4	1.0	mA
Active Supply Current		3.0	6.0	10.0	mA
VCC Clamp Voltage	ICC=25mA	30	33	36	V
VCC Turn-On Threshold		14.5	16.3	17.5	V
VCC Turn-Off Threshold		10.5	11.5	13.0	V
VCC Threshold Hysteresis		3	5	7	V

DETAILED BLOCK DIAGRAM



PIN DESCRIPTIONS

COMP: COMP is the output of the error amplifier and the input of the PWM comparator. To limit PWM on-time, this pin is clamped to approximately 10V. To implement soft start, the COMP pin can be pulled low and ramped up with a PNP transistor, a capacitor, and a resistor.

GND: Ground for all functions is through this pin.

ISET: The dominant function of this pin is to program RAMP charging current. RAMP charging current is approximately 5V divided by the external resistor placed from ISET to ground. Resistors in the range of 10kΩ to 50kΩ are recommended, producing currents in the range of 100μA to 500μA.

A second function of ISET is as reference output. The ISET pin is normally regulated to 5V ±10%. It is critical that this pin only see the loading of the RAMP programming resistor, but a high input-impedance comparator or amplifier may be connected to this pin or to a tap on the RAMP programming resistor if required.

The third function of the ISET pin is as a FAULT output. In the event of an over-current fault, the ISET pin is forced to approximately 9V by the fault comparator. This can be used to trip an external protection circuit which can disable the load or start a fault restart cycle.

ISNS: This input to the zero and over current comparators is specially built to allow operation over a ±5V dynamic range. In noisy systems or systems with very high Q inductors, it is desirable to filter the signal entering the ISNS input to prevent premature restart or fault cycles. For best

accuracy, ISNS should be connected to a current sense resistor through no more than 200 ohms.

OUT: The output of a high-current power driver capable of driving the gate of a power MOSFET with peak currents exceeding ±500mA. To prevent damage to the power MOSFET, the OUT pin is internally driven by a 12V supply. However, lead inductance between the OUT pin and the load can cause overshoot and ringing. External current boost transistors will increase this overshoot and ringing. If there is any significant distance between the IC and the MOSFET, external clamp diodes and/or series damping resistors may be required. OUT is actively held low when the VCC is below the UVLO threshold.

RAMP: A controlled on-time PWM requires a timer whose time can be modulated by an external voltage. The timer current is programmed by a resistor from ISET to GND. A capacitor from RAMP to GND sets the on time in conjunction with the voltage on COMP. Recommended values for the timer capacitors are between 100pF and 1nF.

VCC: VCC is the logic and control power connection for this device. VCC current is the sum of active device supply current and the average OUT current. Knowing the maximum operating frequency and the MOSFET gate charge (Q_g), average OUT current can be estimated by:

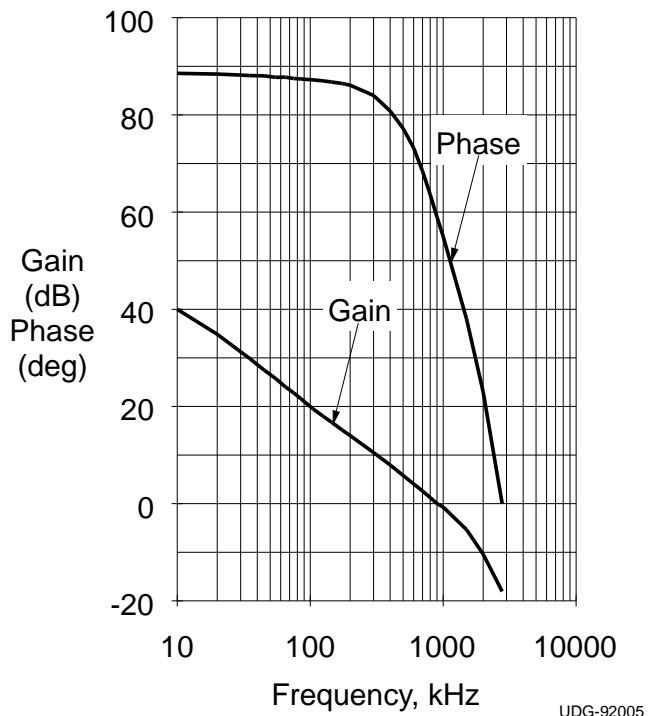
$$I_{OUT} = Q_g \times F$$

To prevent noise problems, bypass VCC to GND with both a ceramic and an electrolytic capacitor.

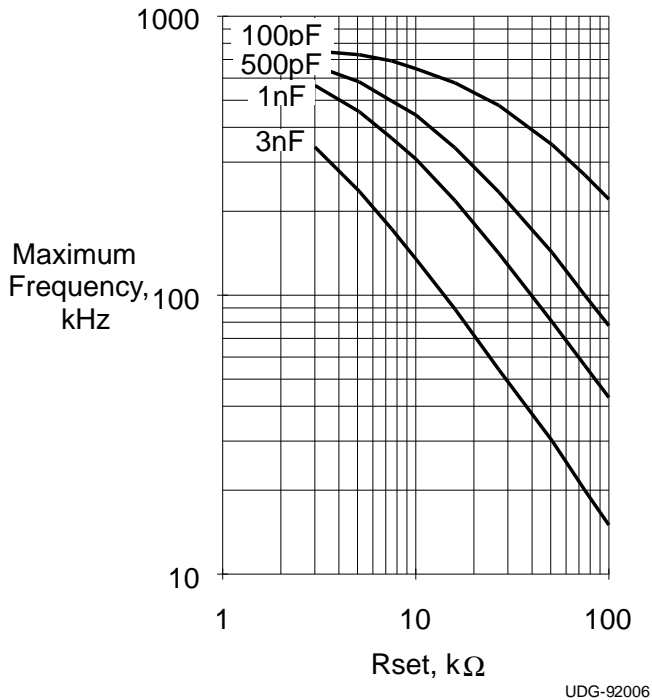
VFB: VFB is the error amplifier inverting input. This input serves as both the voltage sense input to the error amplifier

TYPICAL CHARACTERISTICS

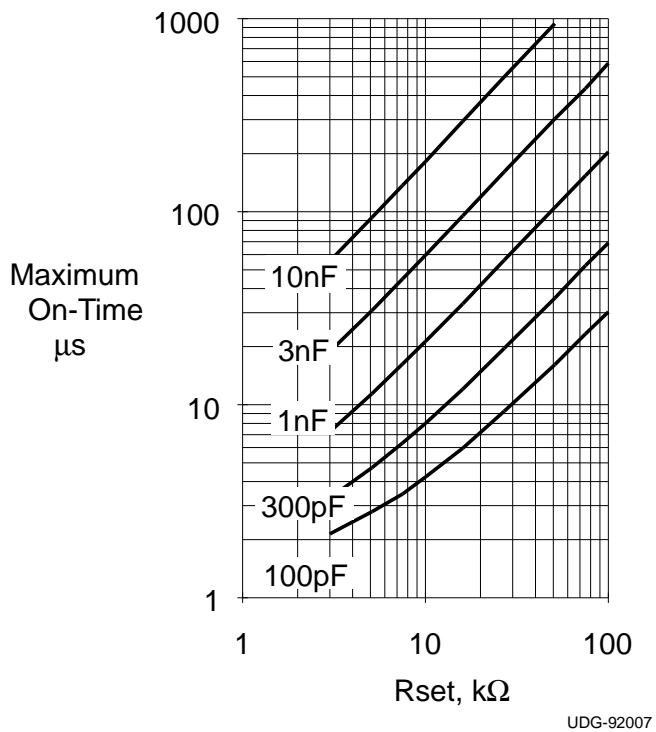
Error Amplifier Gain and Phase



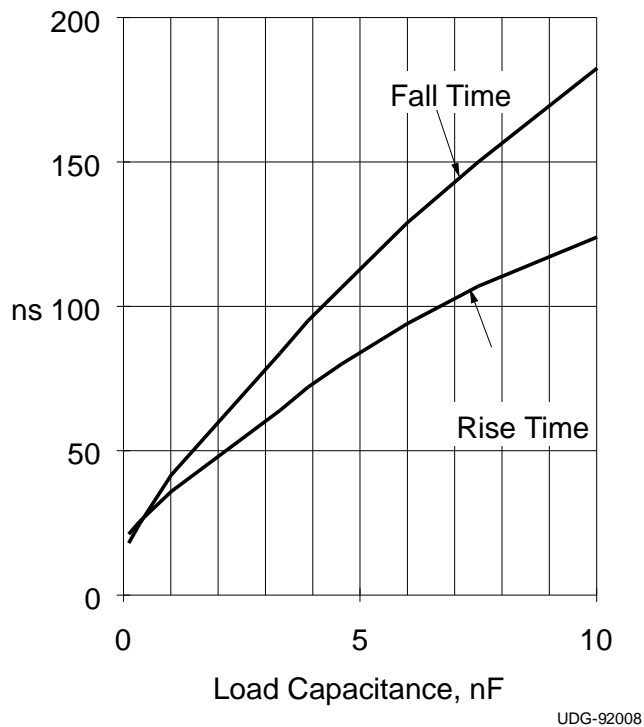
Max Frequency vs. Rset and Ct



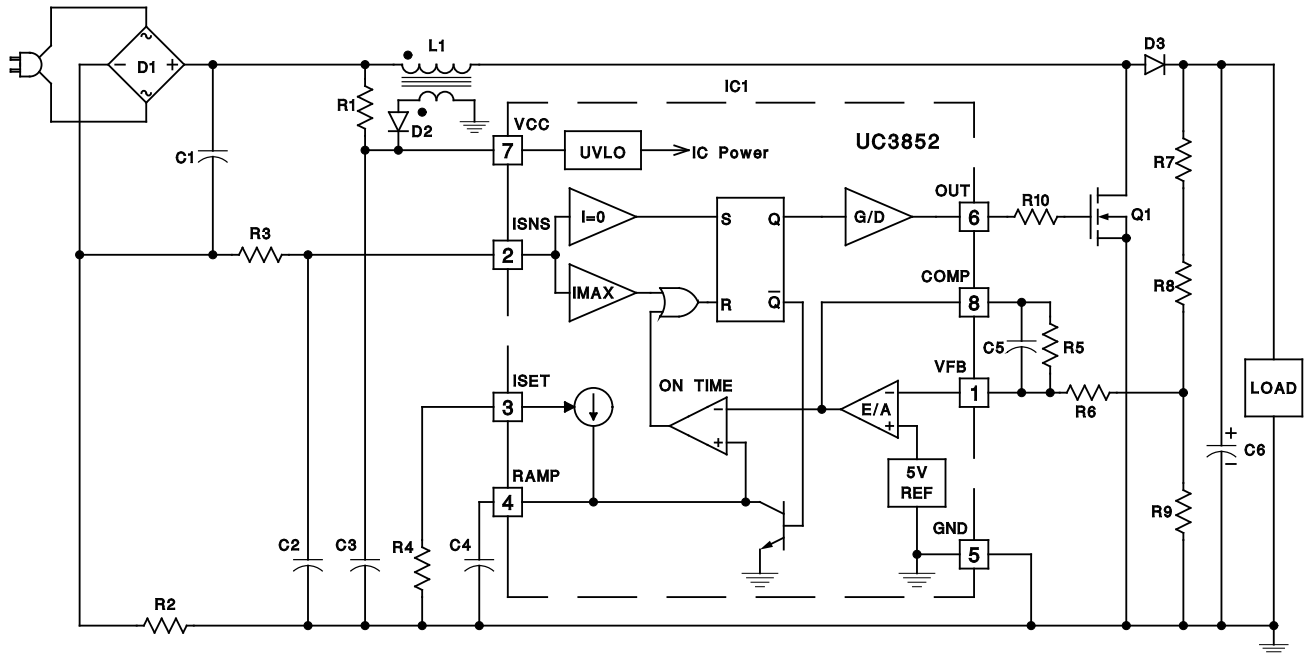
Max On-Time vs. Rset and Ct



OUT Rise and Fall Time



APPLICATION INFORMATION: A 100 Watt Power Factor Preregulator



UDG-92004

This circuit demonstrates a complete power factor preregulator based on the UC3852. This preregulator will supply up to 100 watts at 400VDC and exhibit power factor greater than 0.995 with less than 10% total harmonic distortion. Operating input range is 90V to 160V RMS at 50Hz to 60Hz.

This design is intentionally simple, yet fully functional. The UC3852 can also be used in designs featuring soft start, over-voltage protection, wide power-line voltage operation, and fault latching. For more information on applying the UC3852, refer to Unitrode Application Note U-132.

PARTS LIST

C1	0.47 μ F/250VAC X2 Class Polyester	Q1	IRF830 4.5A/500V 1.5 Ω Power FET
C2	1nF/16V Ceramic	L1	680 μ H (Renco RL3792 with 10 Turn 24 AWG Secondary)
C3	68 μ F/35V Aluminum Electrolytic	R1	150k Ω , 1/4W
C4	180pF/16V Ceramic	R2	0.2 Ω , 1/2W Carbon Composition
C5	0.1 μ F/16V Polyester or Ceramic	R3	10 Ω , 1/4W
C6	82 μ F/450V Aluminum Electrolytic	R4	13.3k Ω , 1/4W
D1	2A/500V Bridge Rectifier (Collmer KBPC106 or Powertex MB11A02V60)	R5	1M Ω , 1/4W
D2	100mA/50V Switching Diode (1N4148)	R6	20k Ω , 1/4W
D3	2A/500V 250ns Recovery-Time Rectifier (Motorola MR856)	R7	200k Ω , 1/2W
IC1	UC3852N Power Factor Controller IC	R8	200k Ω , 1/2W

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UC1852J	OBSOLETE	CDIP	J	8		TBD	Call TI	Call TI
UC1852J883B	OBSOLETE	CDIP	J	8		TBD	Call TI	Call TI
UC2852D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2852DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2852DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2852DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC2852N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC2852NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3852D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3852DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3852DTR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3852DTRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UC3852N	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type
UC3852NG4	ACTIVE	PDIP	P	8	50	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

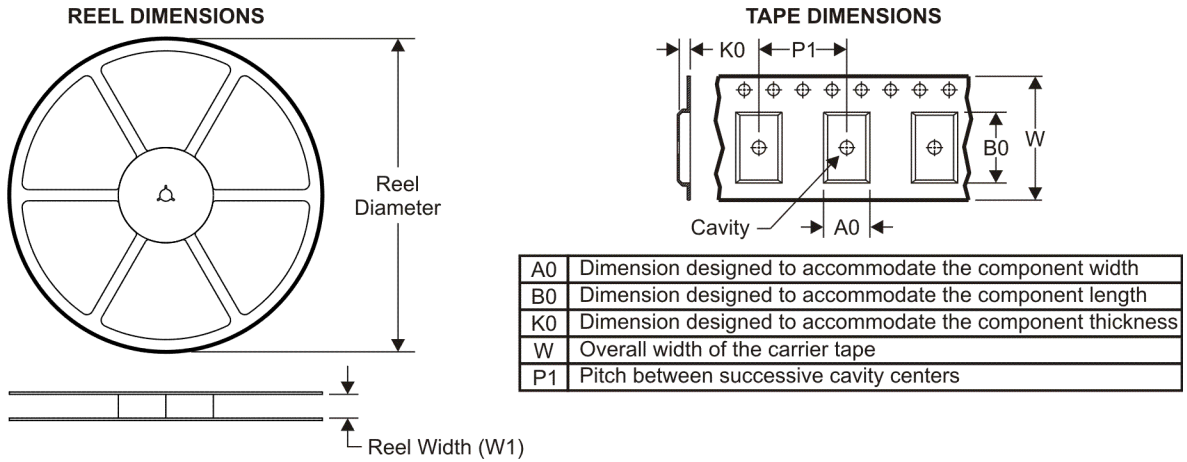
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2852DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC3852DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2852DTR	SOIC	D	8	2500	346.0	346.0	29.0
UC3852DTR	SOIC	D	8	2500	346.0	346.0	29.0

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